



Wafer Dicing Machine

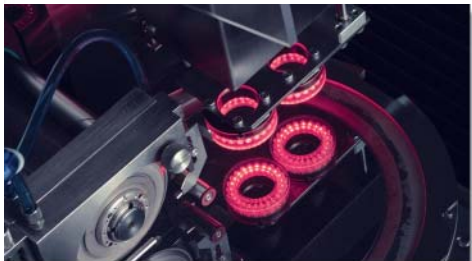
A-WD-10B

This multipurpose dicing machine realizes ease of use with the adaptation of the much sought-after space saving factor, slide cover system and function management system.

- The Z-axis drive unit encoder system stepping motor guarantees high accuracy and reliability, and the X- and Y- axis slide section has a high accuracy, high rigidity linear guide.
- Simultaneous 2-axis control of X- and Y-axis and high throughput, with a max. speed of X-axis: 450mm/s, Y-axis: 80mm/s and Z- axis: 40 mm/s.
- A conveniently-located compact operating panel, rubber switch and jog dial optimized to the operation type (one hand operation) are used; an LCD panel is also used.

Common usages

Electronic parts (SMD, HIC, Piezo device, etc)
Semiconductors (Si, GaAs, etc)
Glass (crystal, filter, small LCD, etc)
Thermal Head (Small), New Materials



The clarity of the microscope image and the accuracy of image recognition are improved by LED lighting.
(Ring lighting specification: Optional)



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User-friendly Operating Panel



Operation Display

Function Management System

Registering frequently used functions and creating shortcuts improves operability.



A-WD-10B SPECIFICATIONS

Work Size		162 x 162 mm
X axis	Movement stroke	290 mm
	Cutting speed	0.1 - 450 mm/s
Y axis	Movement stroke	162 mm
	Maximum speed	80 mm/s
	Positioning accuracy	5 μm
Z axis	Movement stroke	35 mm
	speed	40 mm/s
	Resolution	0.0001 mm
θ axis	Rotation range	290°
	Positioning resolution	0.00018°(0.648")
Alignment	Microscope type	Split-field type
	Camera, LCD	Standard (12.1" magnification 211 x)
Spindle	Type	Air spindle with a built-in high-frequency AC motor
	Maximum revs.	40,000 min ⁻¹
	Maximum output	900 W
Others	Power supply	200/220V AC , 3 phase
	Power consumption	2.0 kVA
	Air supply	0.55 - 0.6 MPa, 180 l /min
	Spindle coolant water	0.2 - 0.5 MPa, 1.5 l /min
	Cutting water	0.2 - 0.5 MPa, 5 l /min max
	Equipment dimensions, weight	650 ^W x 890 ^D x 1,300 ^H mm, 500 kg

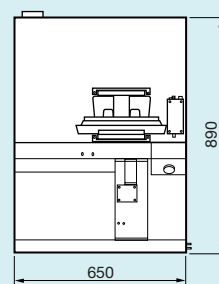
Main Options

- Non-contact optical cutter setting unit
- Blade breakage detector
- 3" flange compatibility
- Y-scale positioning accuracy:2 μm/162 mm
- Cover interlock
- Ring lighting
- Middle power spindle
- 3 color indication lamp
- Mist fan
- CE marking
- A-CS-100A (Spin Cleaner/Dryer)



A-CS-100A (Optional)

Dimensions (mm)



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Specifications and other descriptions may be changed for product improvement without any notice.